

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Printed board assemblies –  
Part 1: Generic specification – Requirements for soldered electrical and  
electronic assemblies using surface mount and related assembly technologies**

**Ensembles de cartes imprimées –  
Partie 1: Spécification générique – Exigences relatives aux ensembles  
électriques et électroniques brasés utilisant les techniques de montage en  
surface et associées**



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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARD ASSEMBLIES –****Part 1: Generic specification –  
Requirements for soldered electrical and electronic assemblies  
using surface mount and related assembly technologies**

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International Standard IEC 61191-1 has been prepared by IEC technical committee 91: Electronics assembly technology.

This second edition cancels and replaces the first edition, published in 1998, and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- reference standard IEC 61192-1 has been replaced by IPC-A-610;
- some of the terminology has been updated;
- references to IEC standards have been corrected;
- the use of lead-free alloys in the assembly have been added.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1089A/FDIS	91/1098/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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